

## TPA6133A2 138-mW DirectPath™ Stereo Headphone Amplifier

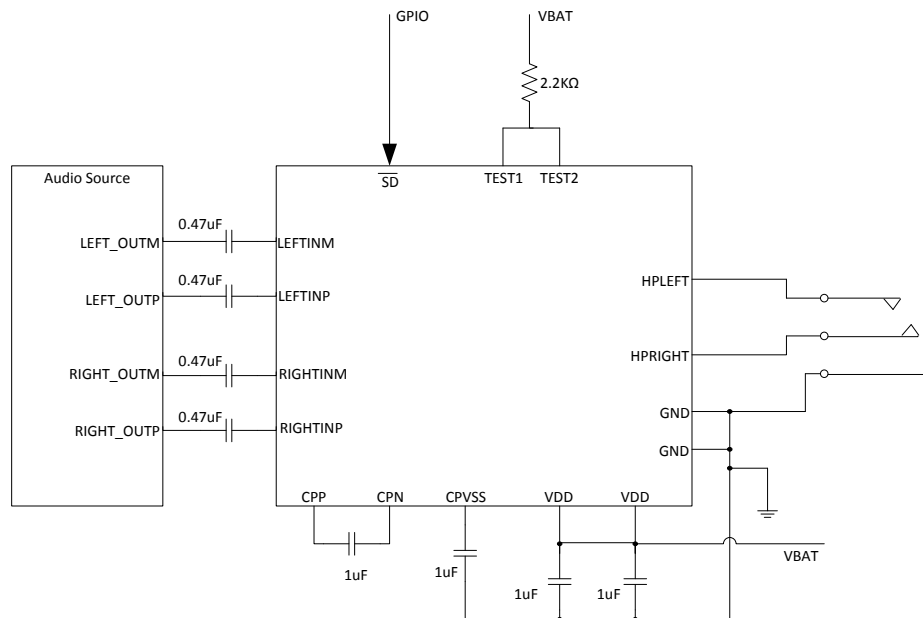
### 1 Features

- DirectPath™ Ground-Referenced Outputs
  - Eliminates Output DC Blocking Capacitors
  - Reduces Board Area
  - Reduces Component Height and Cost
  - Full Bass Response Without Attenuation
- Power Supply Voltage Range: 2.5 V to 5.5 V
- High Power Supply Rejection Ratio (>100 dB PSRR)
- Differential Inputs for Maximum Noise Rejection (69 dB CMRR)
- High-Impedance Outputs When Disabled
- Advanced Pop and Click Suppression Circuitry
- GPIO Control for Shutdown
- 20 Pin, 4 mm x 4 mm WQFN Package

### 2 Applications

- Mobile Phones
- Audio Headsets
- Notebook Computers
- High Fidelity Applications

### 4 Simplified Application Diagram



### 3 Description

The TPA6133A2 is a stereo DirectPath™ headphone amplifier with GPIO control. The TPA6133A2 has minimal quiescent current consumption, with a typical  $I_{DD}$  of 4.2 mA, making it optimal for portable applications. The GPIO control allows the device to be put in a low power shutdown mode.

The TPA6133A2 is a high fidelity amplifier with an SNR of 93 dB. A PSRR greater than 100 dB enables direct-to-battery connections without compromising the listening experience. The output noise of 12  $\mu\text{Vrms}$  (typical *A-weighted*) provides a minimal noise background during periods of silence. Configurable differential inputs and high CMRR allow for maximum noise rejection in the noisy environment of a mobile device.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TPA6133A2	WQFN (20)	4.00 mm x 4.00 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.



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## 5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

### Changes from Revision A (August 2014) to Revision B

Page

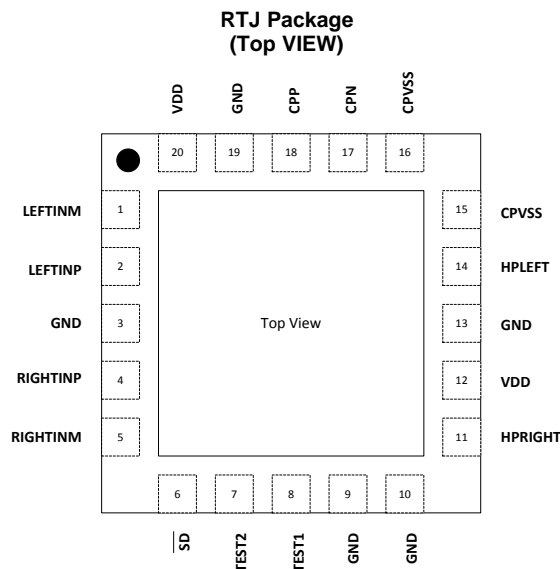
• Changed "PIN QFN" To: "NUMBER" in the Pin Functions table .....	<b>3</b>
• Added a NOTE to the Applications and Implementation section .....	<b>13</b>
• Added new paragraph to the Application Information section .....	<b>13</b>

### Changes from Original (June 2013) to Revision A

Page

• Added Handling Rating table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section .....	<b>1</b>
• Added the Device Information Table .....	<b>1</b>
• Moved "Minimum Load Impedance" From the Absolute Maximum Ratings table To the Recommended Operating Conditions table .....	<b>4</b>
• Added the Thermal Information Table .....	<b>4</b>
• Changed text in the Overview section From: "toggling the $\overline{SD}$ pin to logic 1." To: "asserting the $\overline{SD}$ pin to logic 1." .....	<b>10</b>
• Changed text in the Headphone Amplifier section From: "the output signal is severely clipped" To: "power consumption will be higher" .....	<b>11</b>
• Added the Optional Test Setup section .....	<b>15</b>
• Added the Layout Example image .....	<b>17</b>

## 6 Pin Configuration and Functions



### Pin Functions

PIN		INPUT, OUTPUT, POWER	DESCRIPTION
NAME	NUMBER		
LEFTINM	1	I	Left channel negative differential input. Impedance must be matched to LEFTINP. Connect the left input to LEFTINM when using single-ended inputs.
LEFTINP	2	I	Left channel positive differential input. Impedance must be matched to LEFTINM. AC ground LEFTINP near signal source while maintaining matched impedance to LEFTINM when using single-ended inputs.
RIGHTINP	4	I	Right channel positive differential input. Impedance must be matched to RIGHTINM. AC ground RIGHTINP near signal source while maintaining matched impedance to RIGHTINM when using single-ended inputs.
GND	3, 9, 10, 13	P	Analog ground. Must be connected to common supply GND. It is recommended that this pin be used to decouple $V_{DD}$ for analog. Use pin 13 to decouple pin 12 on the QFN package.
RIGHTINM	5	I	Right channel negative differential input. Impedance must be matched to RIGHTINP. Connect the right input to RIGHTINM when using single-ended inputs.
$\overline{SD}$	6	I	Shutdown. Active low logic. 5V tolerant input.
TEST2	7	I	Factory test pins. Pull up to $V_{DD}$ supply. See Applications Diagram.
TEST1	8	I	Factory test pins. Pull up to $V_{DD}$ supply. See Applications Diagram.
HPRIGHT	11	O	Headphone light channel output. Connect to the right terminal of the headphone jack.
$V_{DD}$	12	P	Analog $V_{DD}$ . $V_{DD}$ must be connected to common $V_{DD}$ supply. Decouple with its own 1- $\mu$ F capacitor to analog ground (pin 13).
HPLEFT	14	O	Headphone left channel output. Connect to left terminal of headphone jack.
CPVSS	15, 16	P	Negative supply generated by the charge pump. Decouple to pin 19 or a GND plane. Use a 1 $\mu$ F capacitor.
CPN	17	P	Charge pump flying capacitor negative terminal. Connect one side of the flying capacitor to CPN.
CPP	18	P	Charge pump flying capacitor positive terminal. Connect one side of the flying capacitor to CPP.
GND	19	P	Charge pump ground. GND must be connected to common supply GND. It is recommended that this pin be decoupled to the $V_{DD}$ of the charge pump pin (pin 20 on the QFN).
$V_{DD}$	20	P	Charge pump voltage supply. $V_{DD}$ must be connected to the common $V_{DD}$ voltage supply. Decouple to GND (pin 19) with its own 1 $\mu$ F capacitor.
Thermal pad	Die Pad	P	Solder the thermal pad on the bottom of the QFN package to the GND plane of the PCB. It is required for mechanical stability and will enhance thermal performance.

## 7 Specification

### 7.1 Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range,  $T_A = 25^\circ\text{C}$  (unless otherwise noted)

		MIN	MAX	UNIT
Supply voltage, $V_{DD}$		-0.3	6	V
Input voltage	RIGHTINx, LEFTINx	CPVSS-0.2 V to minimum of (3.6 V, $V_{DD}+0.2$ V)		
	$\overline{SD}$ , TEST1, TEST2	-0.3	7	V
Output continuous total power dissipation		See the <a href="#">Thermal Information</a> Table		
Operating free-air temperature range, $T_A$		-40	85	$^\circ\text{C}$
Operating junction temperature range, $T_J$		-40	150	$^\circ\text{C}$

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 7.2 Handling Ratings

			MIN	MAX	UNIT
$T_{stg}$	Storage temperature range		-65	150	$^\circ\text{C}$
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	-3	3	kV
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	-750	750	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 7.3 Recommended Operating Conditions

			MIN	MAX	UNIT
Supply voltage, $V_{DD}$			2.5	5.5	V
$V_{IH}$	High-level input voltage	TEST1, TEST2, $\overline{SD}$	1.3		V
$V_{IL}$	Low-level input voltage	$\overline{SD}$		0.35	V
Minimum Load Impedance			12.8		$\Omega$
$T_A$	Operating free-air temperature		-40	85	$^\circ\text{C}$

### 7.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		RTJ	UNIT
		20 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	34.8	$^\circ\text{C}/\text{W}$
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	32.5	
$R_{\theta JB}$	Junction-to-board thermal resistance	11.6	
$\Psi_{JT}$	Junction-to-top characterization parameter	0.4	
$\Psi_{JB}$	Junction-to-board characterization parameter	11.6	
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	3.1	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## 7.5 Electrical Characteristics

 $T_A = 25^\circ\text{C}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$ V_{OS} $	Output offset voltage	$V_{DD} = 2.5\text{ V to } 5.5\text{ V}$ , inputs grounded		135	400	$\mu\text{V}$
PSRR	DC Power supply rejection ratio	$V_{DD} = 2.5\text{ V to } 5.5\text{ V}$ , inputs grounded		-101	-85	dB
CMRR	Common mode rejection ratio	$V_{DD} = 2.5\text{ V to } 5.5\text{ V}$		-69		dB
$ I_{IH} $	High-level input current	$V_{DD} = 5.5\text{ V}$ , $V_I = V_{DD}$	TEST1, TEST2		1	$\mu\text{A}$
			$\overline{SD}$		10	
$ I_{IL} $	Low-level input current	$V_{DD} = 5.5\text{ V}$ , $V_I = 0\text{ V}$			1	$\mu\text{A}$
$I_{DD}$	Supply current	$V_{DD} = 2.5\text{ V to } 5.5\text{ V}$ , $\overline{SD} = V_{DD}$		4.2	6	mA
		Shutdown mode, $V_{DD} = 2.5\text{ V to } 5.5\text{ V}$ , $\overline{SD} = 0\text{ V}$		0.08	1	$\mu\text{A}$

## 7.6 Operating Characteristics

 $V_{DD} = 3.6\text{ V}$ ,  $T_A = 25^\circ\text{C}$ ,  $R_L = 16\ \Omega$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$P_O$	Output power	Stereo, Outputs out of phase, THD = 1%, $f = 1\text{ kHz}$ , Gain = +4 dB	$V_{DD} = 2.5\text{ V}$		63	mW
			$V_{DD} = 3.6\text{ V}$		133	
			$V_{DD} = 5\text{ V}$		142	
THD+N	Total harmonic distortion plus noise	$P_O = 35\text{ mW}$	$f = 100\text{ Hz}$		0.0096%	
			$f = 1\text{ kHz}$		0.007%	
			$f = 20\text{ kHz}$		0.0021%	
$k_{SVR}$	Supply ripple rejection ratio	200 mV <sub>pp</sub> ripple, $f = 217\text{ Hz}$		-94.3	-85	dB
		200 mV <sub>pp</sub> ripple, $f = 1\text{ kHz}$		-92		
		200 mV <sub>pp</sub> ripple, $f = 20\text{ kHz}$		-77.1		
$A_V$	Channel DC Gain	$\overline{SD} = V_{DD}$		1.597		V/V
$\Delta A_V$	Gain matching			0.1%		
	Slew rate			0.4		V/ $\mu\text{s}$
$V_n$	Noise output voltage	$V_{DD} = 3.6\text{ V}$ , A-weighted, Gain = +4 dB		12		$\mu\text{V}_{RMS}$
$f_{osc}$	Charge pump switching frequency		300	381	500	kHz
	Start-up time from shutdown			4.8		ms
	Differential input impedance			36.6		k $\Omega$
SNR	Signal-to-noise ratio	$P_O = 35\text{ mW}$		93		dB
	Thermal shutdown	Threshold		180		$^\circ\text{C}$
		Hysteresis		35		$^\circ\text{C}$
$Z_O$	HW Shutdown HP output impedance	$\overline{SD} = 0\text{ V}$ , measured output to ground.		112		$\Omega$
$C_O$	Output capacitance			80		pF

## 7.7 Typical Characteristics

Table 1. Table of Graphs

		Figure
Total harmonic distortion + noise	versus Output power	Figure 1–Figure 4
Total harmonic distortion + noise	versus Frequency	Figure 5–Figure 12
Supply voltage rejection ratio	versus Frequency	Figure 13–Figure 14
Common mode rejection ratio	versus Frequency	Figure 15–Figure 16
Crosstalk	versus Frequency	Figure 17–Figure 18

$C_{(PUMP, DECOUPLE, \text{BYPASS}, CPVSS)} = 1 \mu\text{F}$ ,  $C_1 = 2.2 \mu\text{F}$ .

All THD + N graphs taken with outputs out of phase (unless otherwise noted).

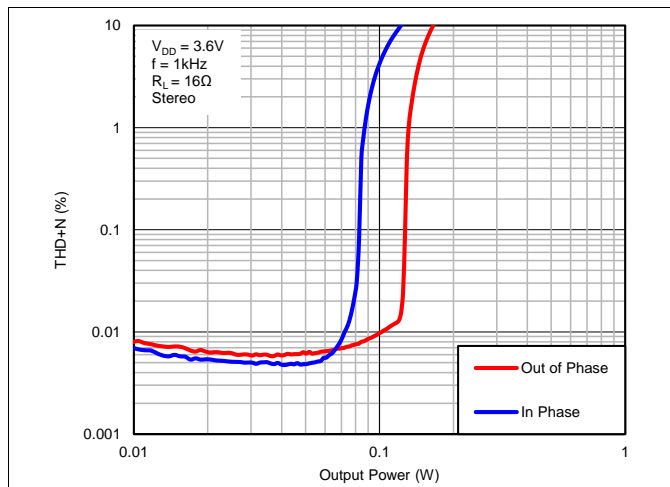


Figure 1. Total Harmonic Distortion + Noise vs Output Power

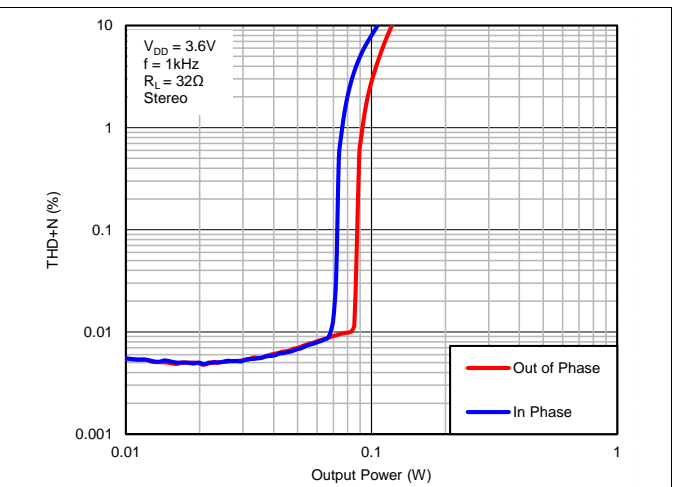


Figure 2. Total Harmonic Distortion + Noise vs Output Power

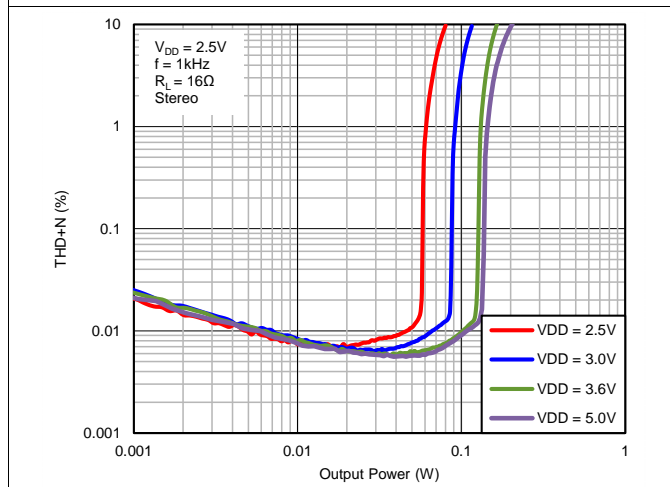


Figure 3. Total Harmonic Distortion + Noise vs Output Power

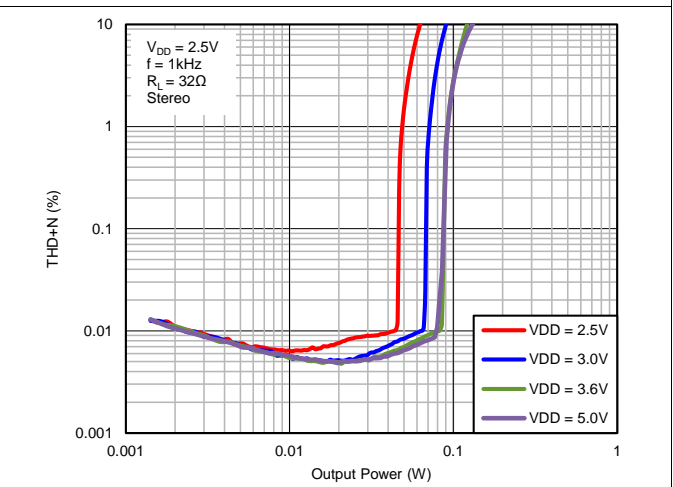


Figure 4. Total Harmonic Distortion + Noise vs Output Power

All THD + N graphs taken with outputs out of phase (unless otherwise noted).

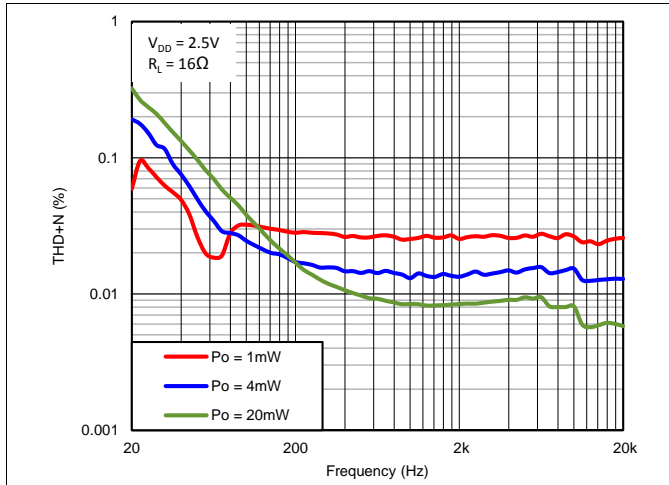


Figure 5. Total Harmonic Distortion + Noise vs Frequency

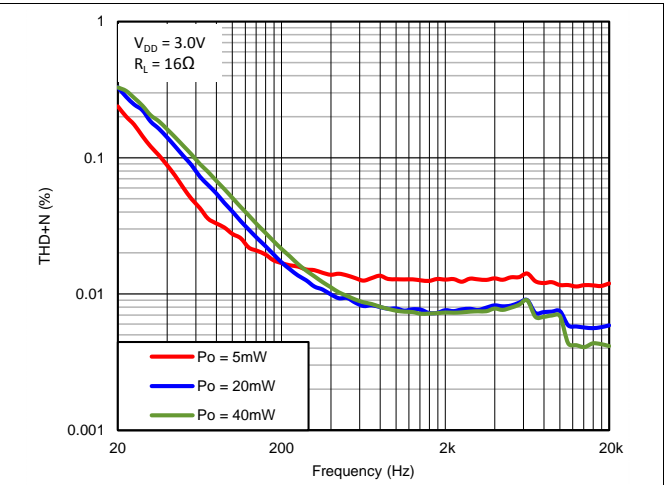


Figure 6. Total Harmonic Distortion + Noise vs Frequency

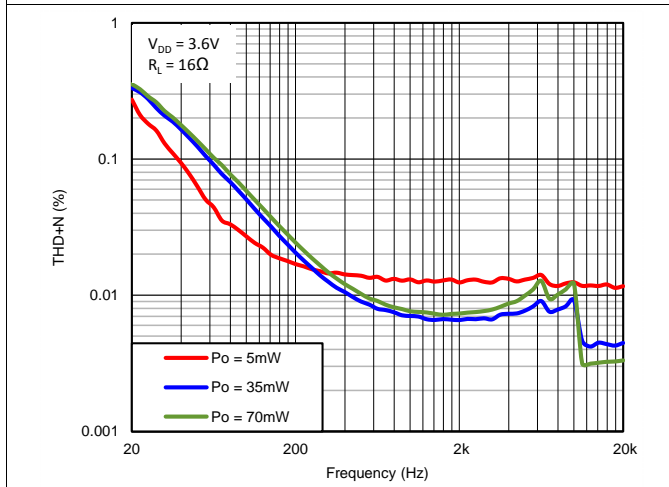


Figure 7. Total Harmonic Distortion + Noise vs Frequency

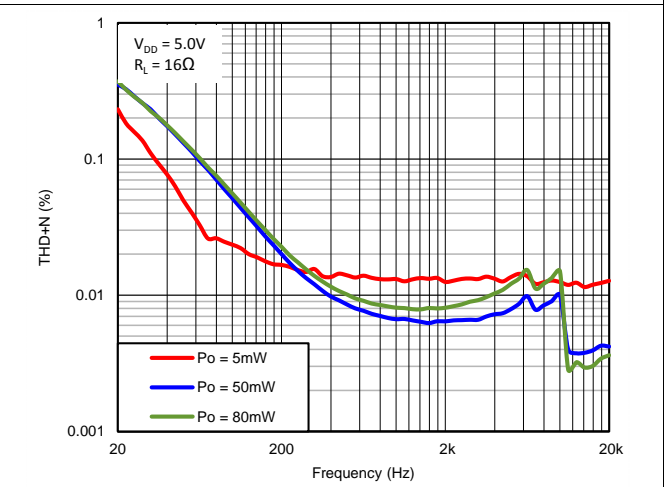


Figure 8. Total Harmonic Distortion + Noise vs Frequency

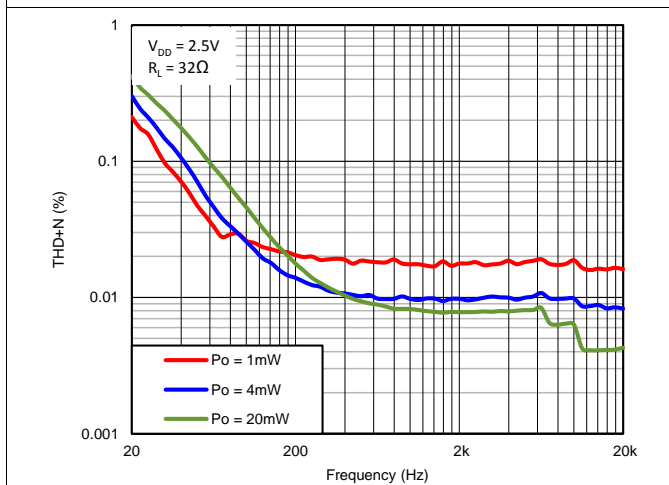


Figure 9. Total Harmonic Distortion + Noise vs Frequency

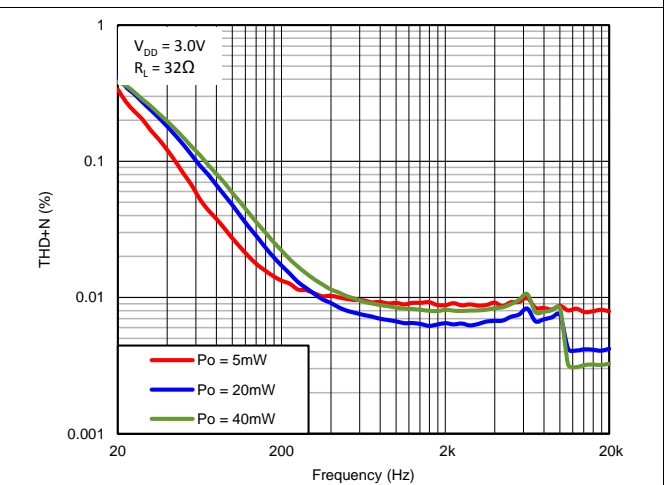
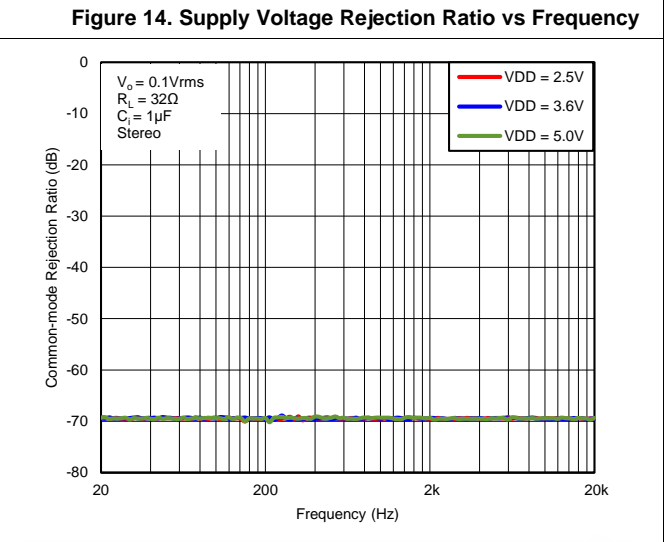
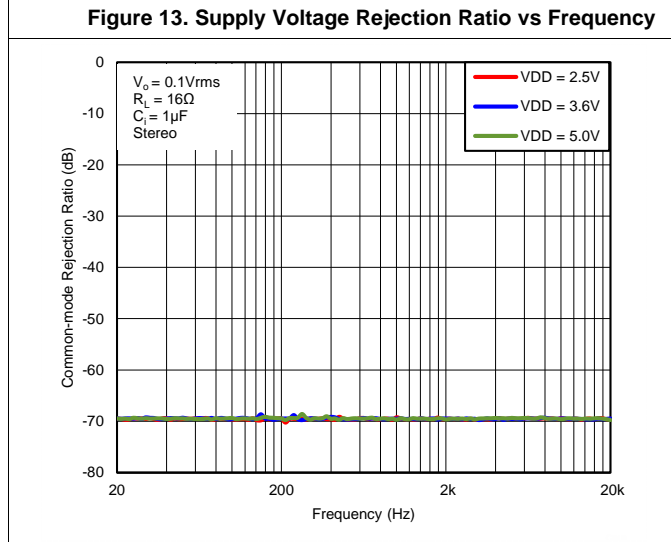
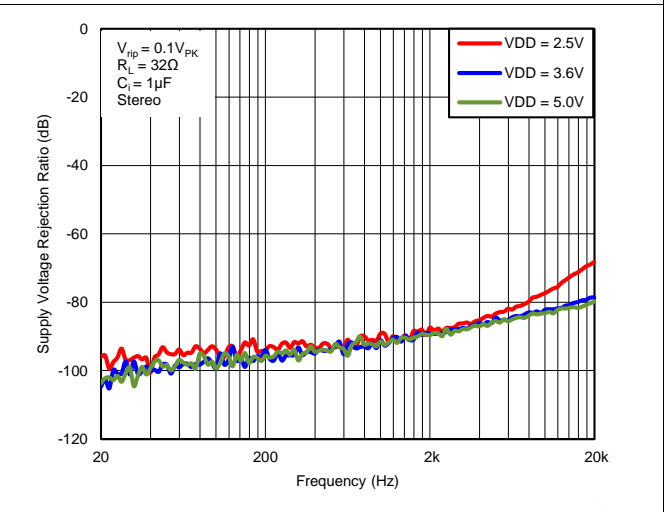
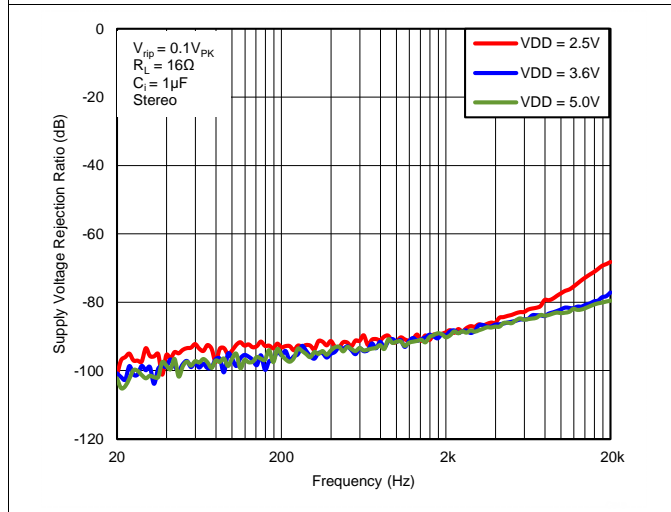
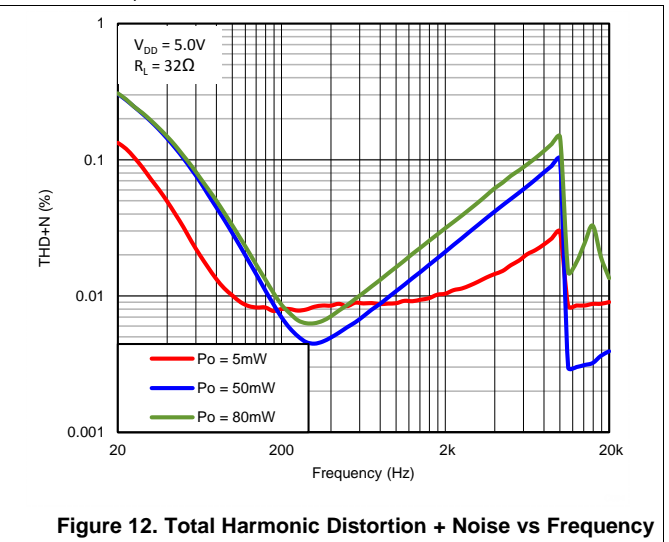
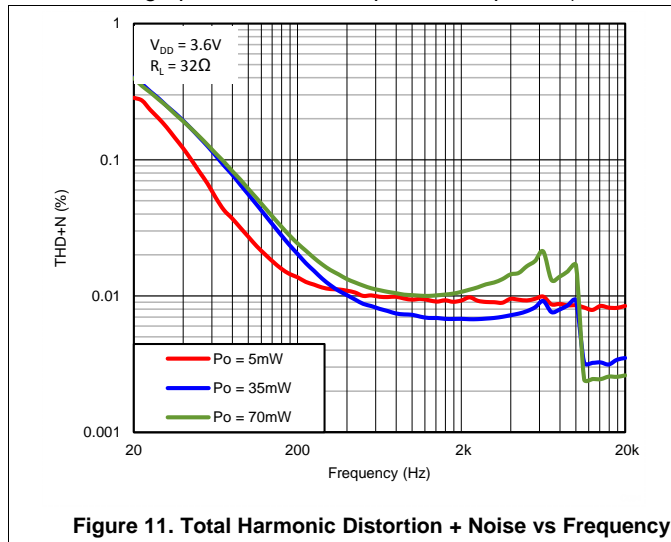


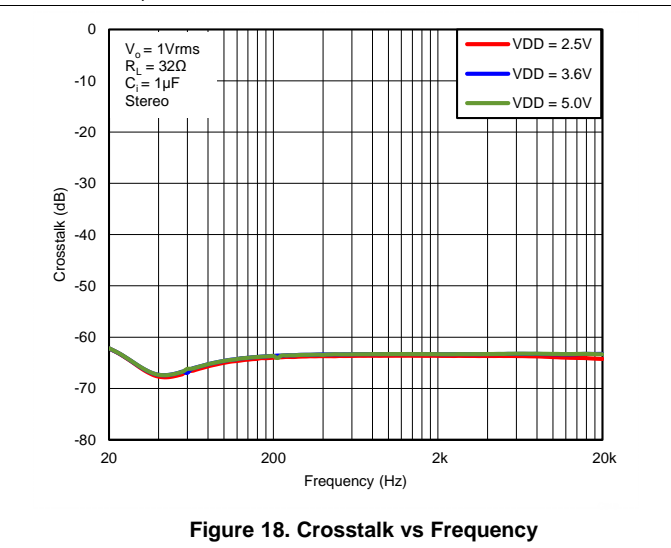
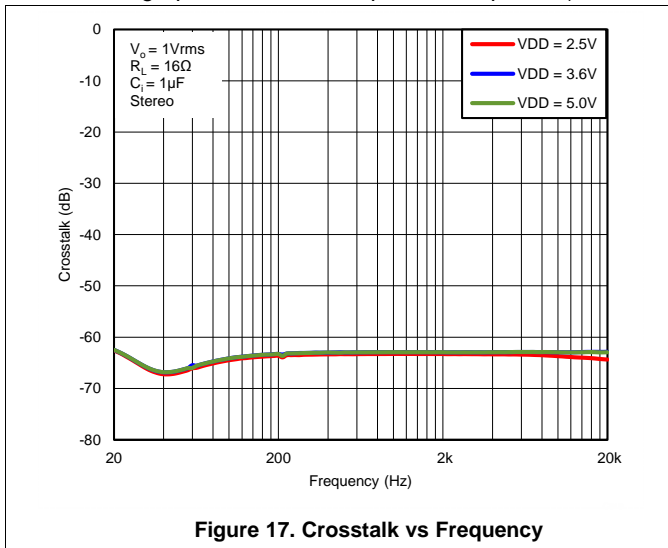
Figure 10. Total Harmonic Distortion + Noise vs Frequency

All THD + N graphs taken with outputs out of phase (unless otherwise noted).





All THD + N graphs taken with outputs out of phase (unless otherwise noted).

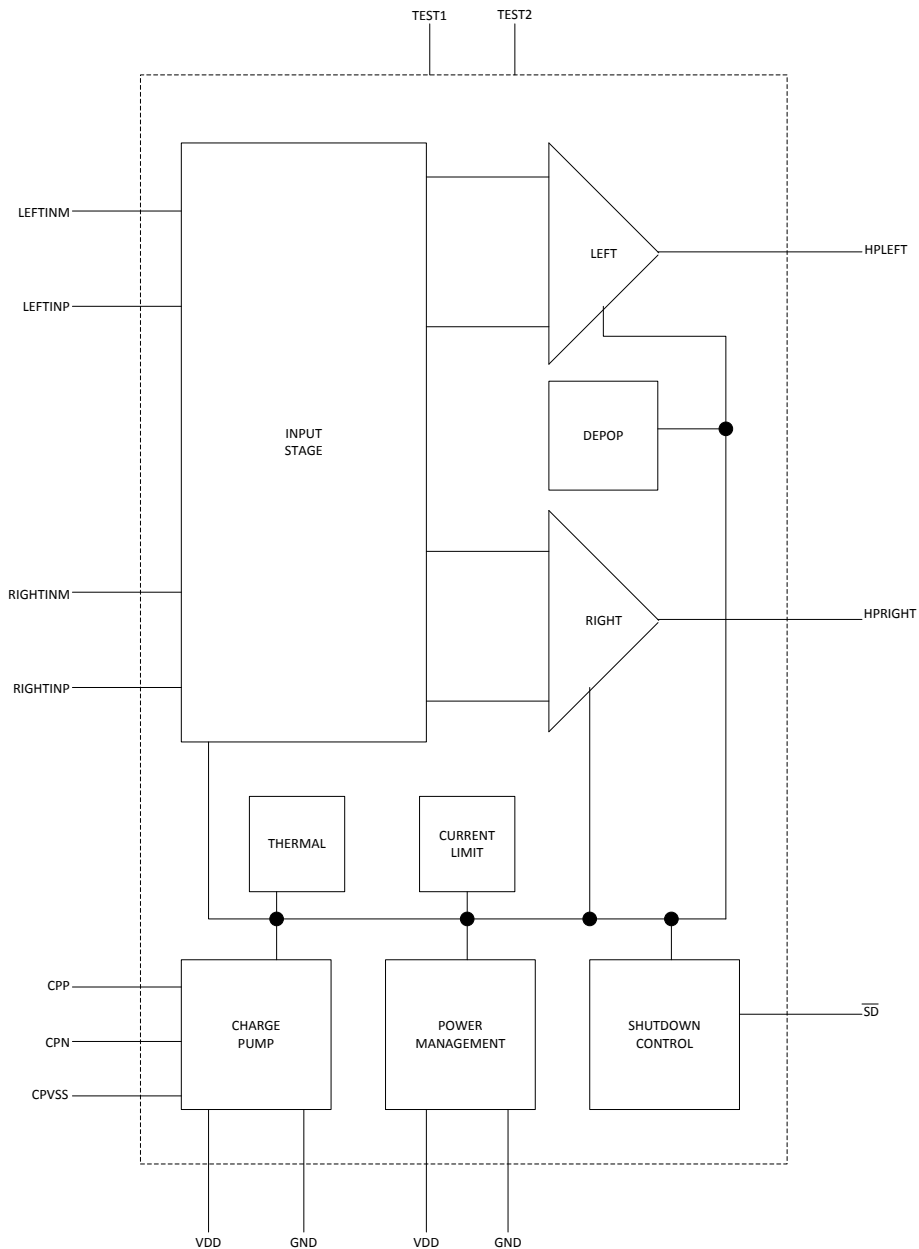


## 8 Detailed Description

### 8.1 Overview

Headphone channels and the charge pump are activated by asserting the  $\overline{SD}$  pin to logic 1. The charge pump generates a negative supply voltage for the output amplifiers. This allows a 0 V bias at the outputs, eliminating the need for bulky output capacitors. The thermal block detects faults and shuts down the device before damage occurs. The current limit block prevents the output current from getting high enough to damage the device. The De-Pop block eliminates audible pops during power-up, power-down, and amplifier enable and disable events.

### 8.2 Functional Block Diagram



## 8.3 Feature Description

### 8.3.1 Headphone Amplifiers

Single-supply headphone amplifiers typically require dc-blocking capacitors. The capacitors are required because most headphone amplifiers have a dc bias on the outputs pin. If the dc bias is not removed, power consumption will be higher, and large amounts of dc current rush through the headphones, potentially damaging them. The top drawing in [Figure 19](#) illustrates the conventional headphone amplifier connection to the headphone jack and output signal.

DC blocking capacitors are often large in value. The headphone speakers (typical resistive values of 16  $\Omega$  or 32  $\Omega$ ) combine with the dc blocking capacitors to form a high-pass filter. [Equation 1](#) shows the relationship between the load impedance ( $R_L$ ), the capacitor ( $C_O$ ), and the cutoff frequency ( $f_c$ ).

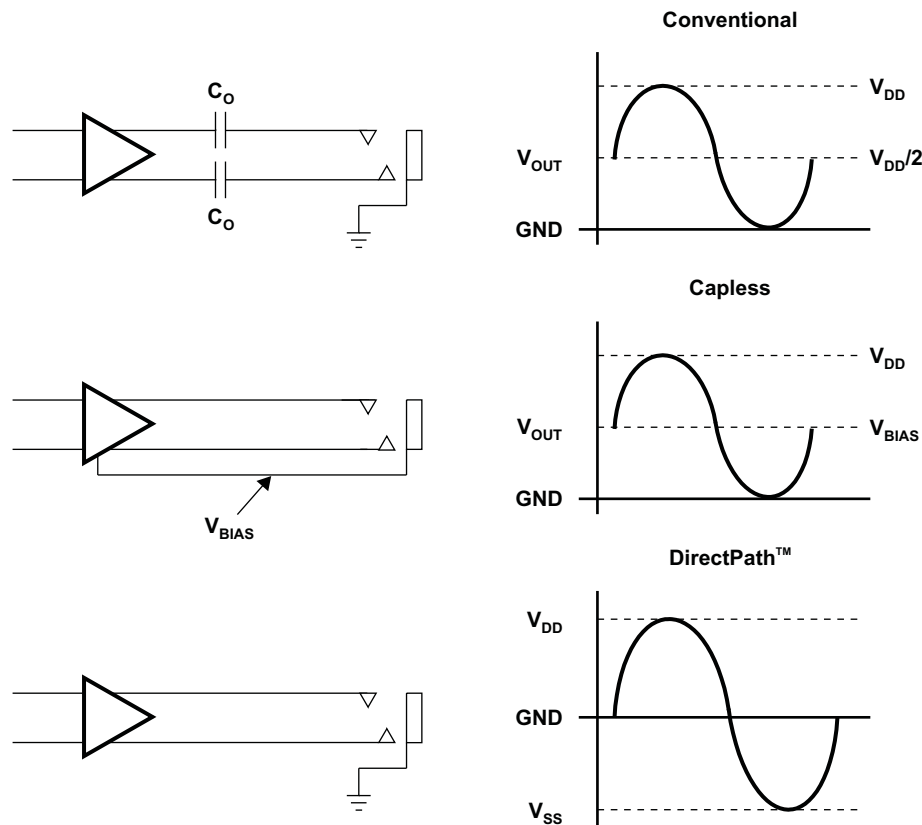
$$f_c = \frac{1}{2\pi R_L C_O} \quad (1)$$

$C_O$  can be determined using [Equation 2](#), where the load impedance and the cutoff frequency are known.

$$C_O = \frac{1}{2\pi R_L f_c} \quad (2)$$

If  $f_c$  is low, the capacitor must then have a large value because the load resistance is small. Large capacitance values require large package sizes. Large package sizes consume PCB area, stand high above the PCB, increase cost of assembly, and can reduce the fidelity of the audio output signal.

Two different headphone amplifier applications are available that allow for the removal of the output dc blocking capacitors. The capless amplifier architecture is implemented in the same manner as the conventional amplifier with the exception of the headphone jack shield pin. This amplifier provides a reference voltage, which is connected to the headphone jack shield pin. This is the voltage on which the audio output signals are centered. This voltage reference is half of the amplifier power supply to allow symmetrical swing of the output voltages. Do not connect the shield to any GND reference or large currents will result. The scenario can happen if, for example, an accessory other than a floating GND headphone is plugged into the headphone connector. See the second block diagram and waveform in [Figure 19](#).

**Feature Description (continued)**

**Figure 19. Amplifier Applications**

The DirectPath™ amplifier architecture operates from a single supply but makes use of an internal charge pump to provide a negative voltage rail. Combining the user provided positive rail and the negative rail generated by the IC, the device operates in what is effectively a split supply mode. The output voltages are now centered at zero volts with the capability to swing to the positive rail or negative rail. The DirectPath™ amplifier requires no output dc blocking capacitors, and does not place any voltage on the sleeve. The bottom block diagram and waveform of [Figure 19](#) illustrate the ground-referenced headphone architecture. This is the architecture of the TPA6133A2.

**8.4 Device Functional Modes**
**8.4.1 Modes of Operation**

The TPA6133A2 supports two modes of operation. When the  $\overline{SD}$  pin is driven to logic 0, the device is in low power mode where the charge pump is powered down, the headphone channel is disabled and the outputs are pulled to ground. When the  $\overline{SD}$  pin is driven to logic 1, the device enters an active mode with charge pump powered up and headphone channel enabled with channel gain of +4dB. The transition from inactive to active and active to inactive states is done softly to avoid audible artifacts.

## 9 Application and Implementation

### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The TPA6133A2 is a stereo DirectPath™ headphone amplifier with GPIO control. The TPA6133A2 has minimal quiescent current consumption, with a typical  $I_{DD}$  of 4.2 mA, making it optimal for portable applications.

### 9.2 Typical Application

Figure 20 shows a typical application circuit for the TPA6133A2 with a stereo headphone jack and supporting power supply decoupling capacitors.

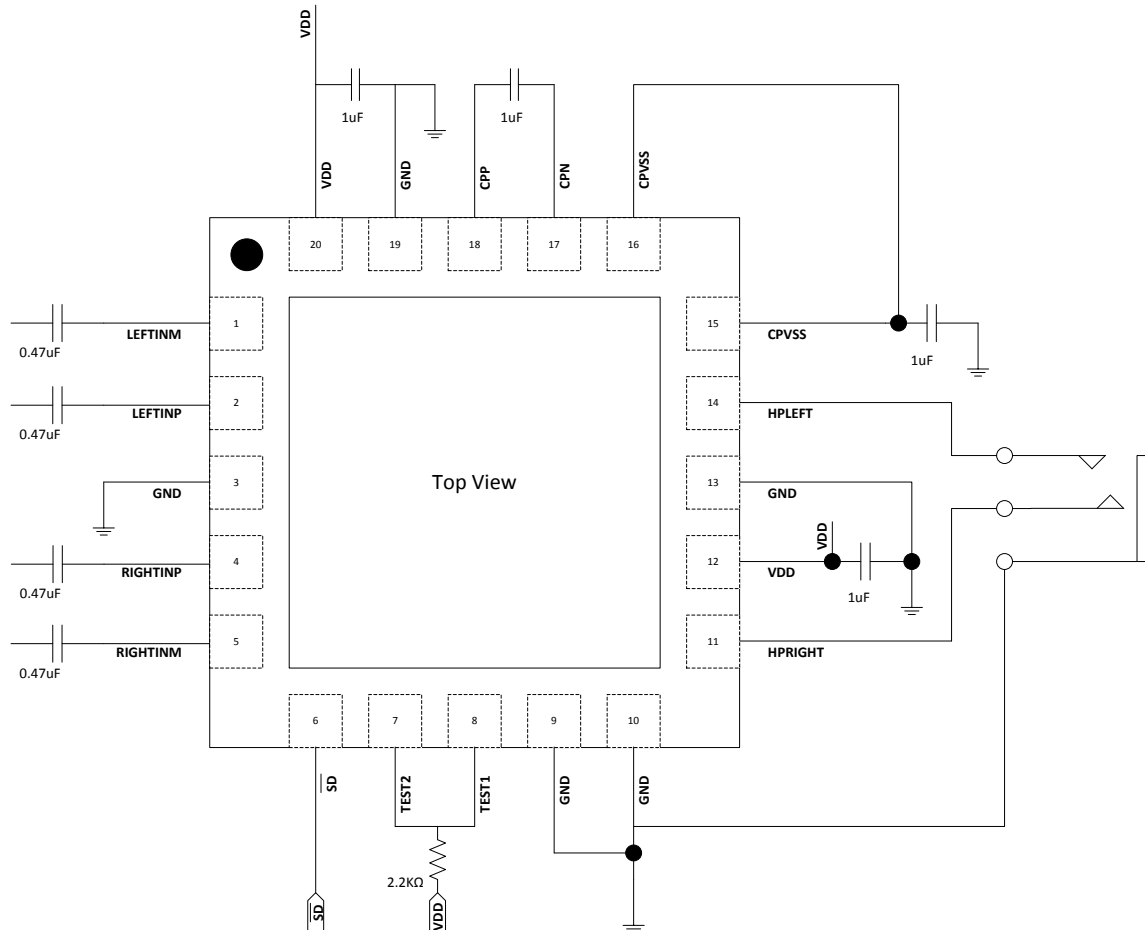


Figure 20. Simplified Applications Circuit

## Typical Application (continued)

### 9.2.1 Design Requirements

For this design example, use the following as the input parameters.

**Table 2. Design Parameters**

DESIGN PARAMETER	EXAMPLE VALUE
Input voltage	2.5 V – 5.5 V
Minimum current limit	4 mA
Maximum current limit	6 mA

### 9.2.2 Detailed Design Procedure

#### 9.2.2.1 Input-Blocking Capacitors

DC input-blocking capacitors block the dc portion of the audio source, and allow the inputs to properly bias. Maximum performance is achieved when the inputs of the TPA6133A2 are properly biased. Performance issues such as pop are optimized with proper input capacitors.

The dc input-blocking capacitors may be removed provided the inputs are connected differentially and within the input common mode range of the amplifier, the audio signal does not exceed  $\pm 3$  V, and pop performance is sufficient.

$C_{IN}$  is a theoretical capacitor used for mathematical calculations only. Its value is the series combination of the dc input-blocking capacitors,  $C_{(DCINPUT-BLOCKING)}$ . Use Equation 3 to determine the value of  $C_{(DCINPUT-BLOCKING)}$ . For example, if  $C_{IN}$  is equal to 0.22  $\mu$ F, then  $C_{(DCINPUT-BLOCKING)}$  is equal to about 0.47  $\mu$ F.

$$C_{IN} = \frac{1}{2} C_{(DCINPUT-BLOCKING)} \quad (3)$$

The two  $C_{(DCINPUT-BLOCKING)}$  capacitors form a high-pass filter with the input impedance of the TPA6133A2. Use Equation 3 to calculate  $C_{IN}$ , then calculate the cutoff frequency using  $C_{IN}$  and the differential input impedance of the TPA6133A2,  $R_{IN}$ , using Equation 4. Note that the differential input impedance changes with gain. The frequency and/or capacitance can be determined when one of the two values are given.

$$f_{C_{IN}} = \frac{1}{2\pi R_{IN} C_{IN}} \quad \text{or} \quad C_{IN} = \frac{1}{2\pi f_{C_{IN}} R_{IN}} \quad (4)$$

If a high pass filter with a -3 dB point of no more than 20 Hz is desired over all gain settings, the minimum impedance would be used in the above equation. The capacitor value by the above equation would be 0.215  $\mu$ F. However, this is  $C_{IN}$ , and the desired value is for  $C_{(DCINPUT-BLOCKING)}$ . Multiplying  $C_{IN}$  by 2 yields 0.43  $\mu$ F, which is close to the standard capacitor value of 0.47  $\mu$ F. Place 0.47  $\mu$ F capacitors at each input terminal of the TPA6133A2 to complete the filter.

#### 9.2.2.2 Charge Pump Flying Capacitor and CPVSS Capacitor

The charge pump flying capacitor serves to transfer charge during the generation of the negative supply voltage. The  $CP_{VSS}$  capacitor must be at least equal to the flying capacitor in order to allow maximum charge transfer. Low ESR capacitors are an ideal selection, and a value of 1  $\mu$ F is typical.

#### 9.2.2.3 Decoupling Capacitors

The TPA6133A2 is a DirectPath™ headphone amplifier that requires adequate power supply decoupling to ensure that the noise and total harmonic distortion (THD) are low. Use good low equivalent-series-resistance (ESR) ceramic capacitors, typically 1.0  $\mu$ F. Find the smallest package possible, and place as close as possible to the device  $V_{DD}$  lead. Placing the decoupling capacitors close to the TPA6133A2 is important for the performance of the amplifier. Use a 10  $\mu$ F or greater capacitor near the TPA6133A2 to filter lower frequency noise signals. The high PSRR of the TPA6133A2 will make the 10  $\mu$ F capacitor unnecessary in most applications.

9.2.2.4 Optional Test Setup

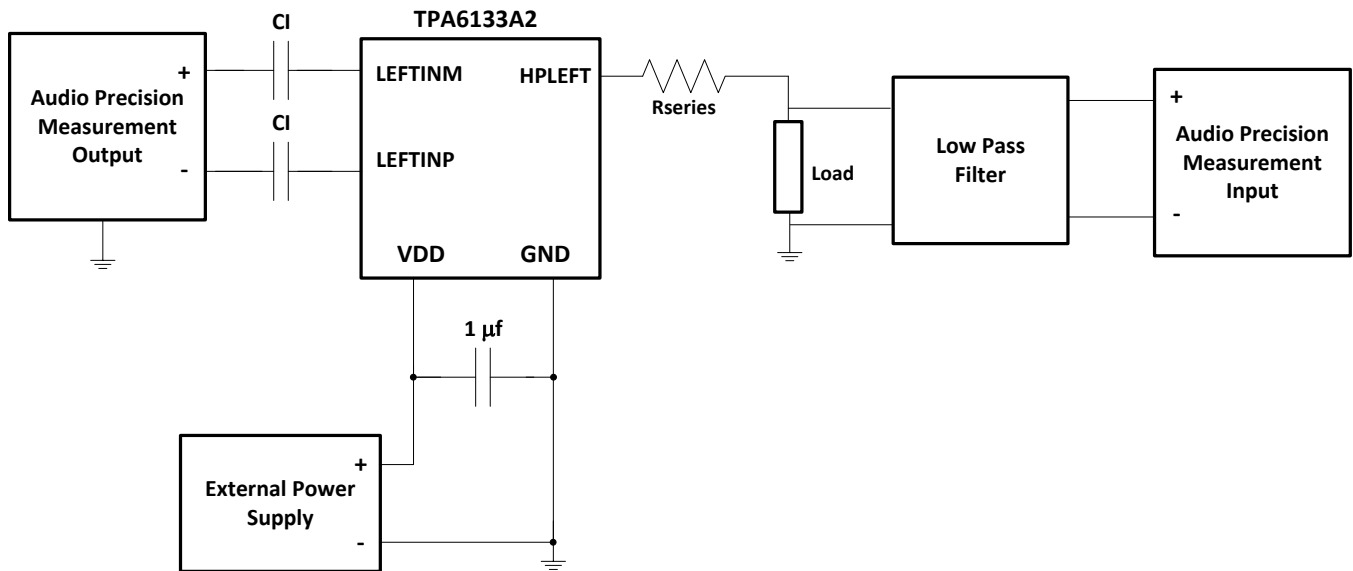
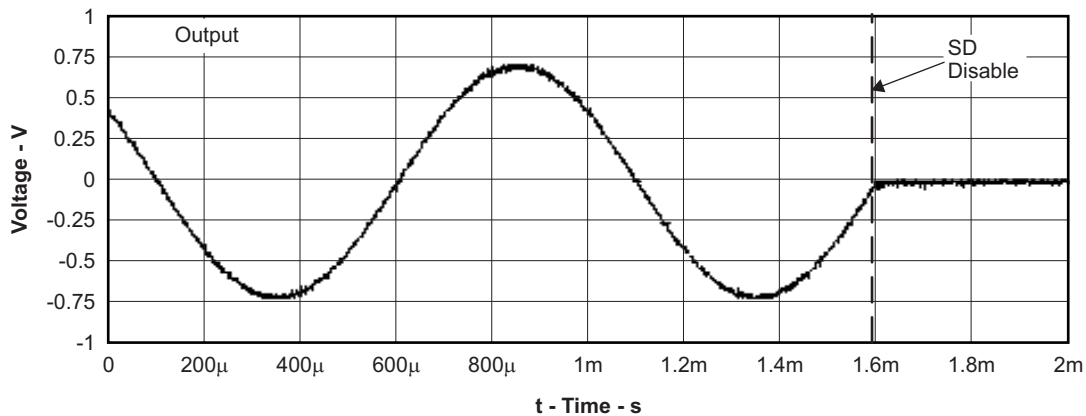


Figure 21. Test Setup

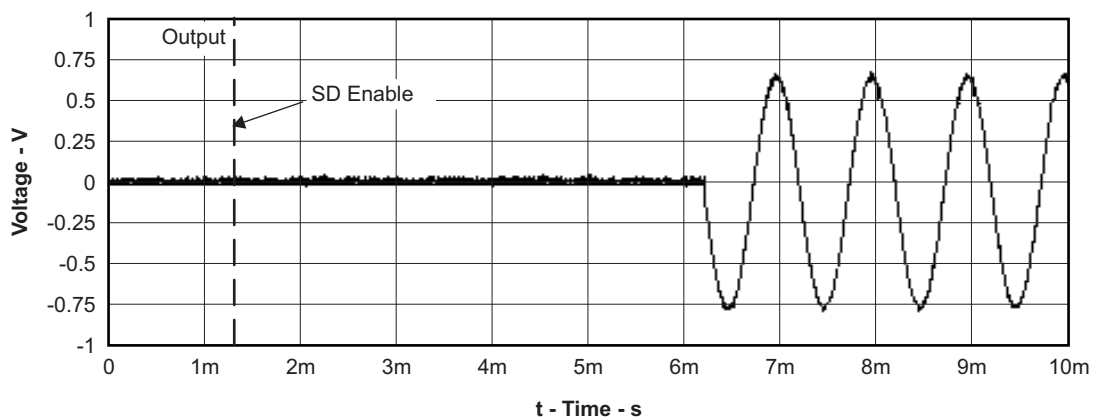
**NOTE**

Separate power supply decoupling caps are used on all VDD and CPVSS Pins  
The low pass filter is used to remove harmonic content above the audible range.

### 9.2.3 Application Curves



**Figure 22. Shutdown Time**



**Figure 23. Startup Time**

## 10 Power Supply Recommendations

The device is designed to operate from an input voltage supply range of 2.5 V to 5.5 V. Therefore, the output voltage range of power supply should be within this range and well regulated. The current capability of upper power should not exceed the max current limit of the power switch.



## 11 Layout

### 11.1 Layout Guidelines

#### 11.1.1 Exposed Pad On TPA6133A2RTJ Package

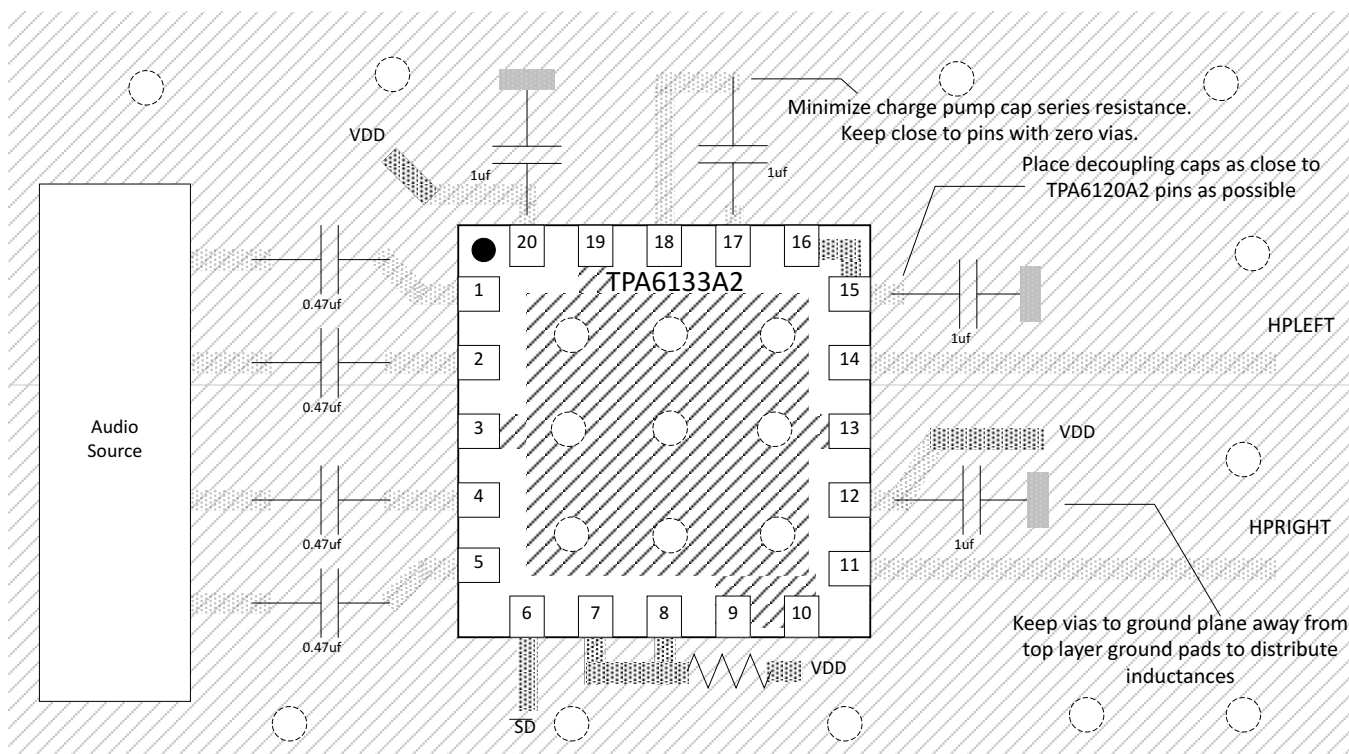
- Solder the exposed metal pad on the TPA6133A2RTJ QFN package to the a pad on the PCB. *The pad on the PCB may be grounded or may be allowed to float (not be connected to ground or power).*
- If the pad is grounded, it must be connected to the same ground as the GND pins (3, 9, 10, 13, and 19). See the layout and mechanical drawings at the end of the datasheet for proper sizing.
- Soldering the thermal pad improves mechanical reliability, improves grounding of the device, and enhances thermal conductivity of the package.

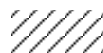
#### 11.1.2 GND Connections


- The GND pin for charge pump should be decoupled to the charge pump  $V_{DD}$  pin, and the GND pin adjacent to the Analog  $V_{DD}$  pin should be separately decoupled to each other.

### 11.2 Layout Example


It is recommended to place a top layer ground pour for shielding around TPA6130A2 and connect to lower main PCB ground plane by multiple vias



 Top Layer Ground Pour and PowerPad

 Pad to top layer ground pour

 Top Layer Signal Traces

 Via to bottom Ground Plane

## 12 Device and Documentation Support

### 12.1 Trademarks

DirectPath is a trademark of Texas Instruments.  
All other trademarks are the property of their respective owners.

### 12.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 12.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TPA6133A2RTJR</a>	Active	Production	QFN (RTJ)   20	3000   LARGE T&R	-	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	SIZ
TPA6133A2RTJR.A	Active	Production	QFN (RTJ)   20	3000   LARGE T&R	-	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	SIZ
TPA6133A2RTJR.B	Active	Production	QFN (RTJ)   20	3000   LARGE T&R	-	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	SIZ
<a href="#">TPA6133A2RTJT</a>	Active	Production	QFN (RTJ)   20	250   SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	SIZ
TPA6133A2RTJT.B	Active	Production	QFN (RTJ)   20	250   SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	SIZ

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPA6133A2RTJR	QFN	RTJ	20	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
TPA6133A2RTJT	QFN	RTJ	20	250	180.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPA6133A2RTJR	QFN	RTJ	20	3000	346.0	346.0	33.0
TPA6133A2RTJT	QFN	RTJ	20	250	210.0	185.0	35.0

## GENERIC PACKAGE VIEW

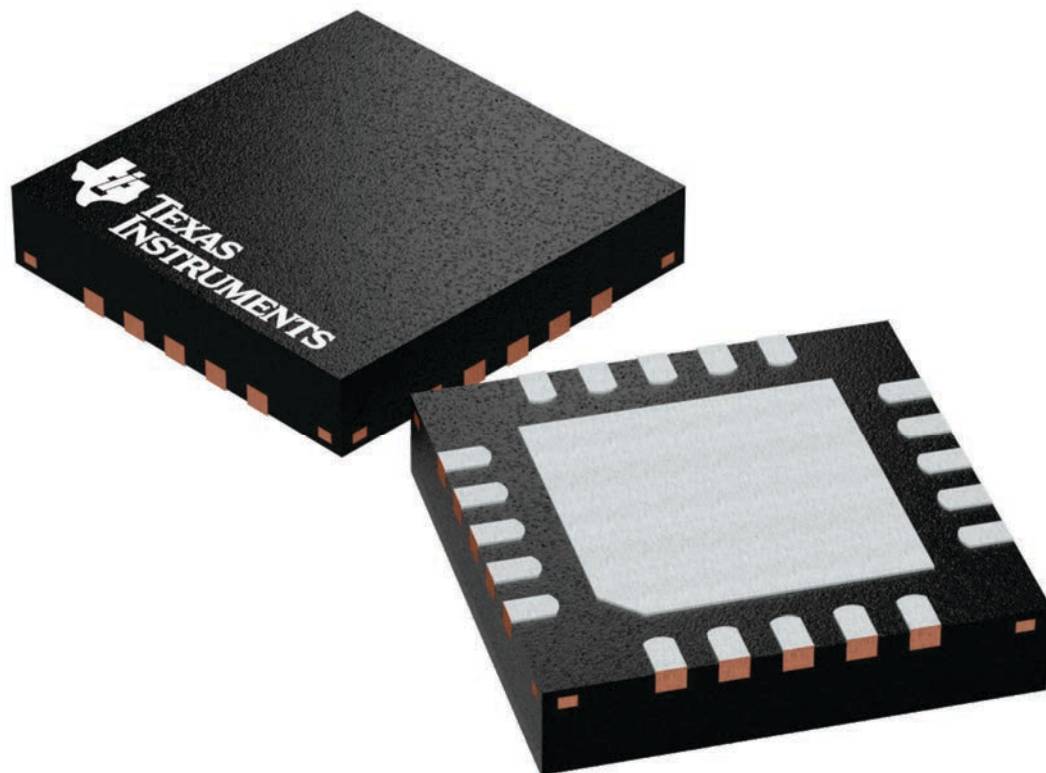
**RTJ 20**

**WQFN - 0.8 mm max height**

4 x 4, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD


This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4224842/A

# DATA BOOK PACKAGE OUTLINE

LEADFRAME EXAMPLE
4222370

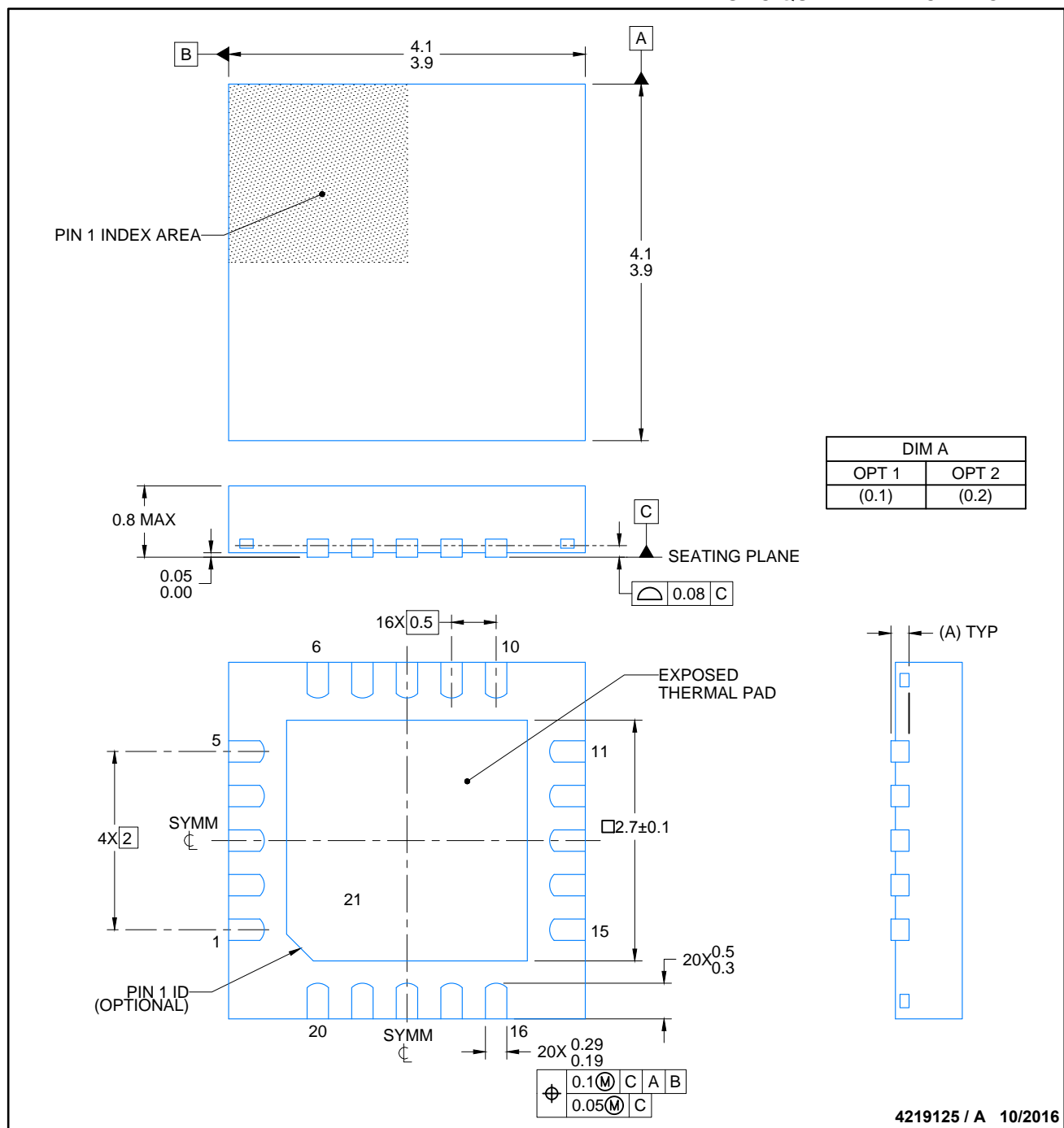
DRAFTSMAN: H. DENG	DATE: 09/12/2016		DIMENSIONS IN MILLIMETERS
DESIGNER: H. DENG	DATE: 09/12/2016	 <b>TEXAS INSTRUMENTS</b> SEMICONDUCTOR OPERATIONS	CODE IDENTITY NUMBER 01295
CHECKER: V. PAKU & T. LEQUANG	DATE: 09/12/2016		<b>ePOD, RTJ0020D / WQFN, 20 PIN, 0.5 MM PITCH</b>
ENGINEER: T. TANG	DATE: 09/12/2016	<b>4219125</b>	
APPROVED: E. REY & D. CHIN	DATE: 10/06/2016		
RELEASED: WDM	DATE: 10/24/2016	SCALE	SIZE
TEMPLATE INFO: EDGE# 4218519	DATE: 04/07/2016	15X	A
		REV	PAGE
		A	1 OF 5

# RTJ0020D

# PACKAGE OUTLINE

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

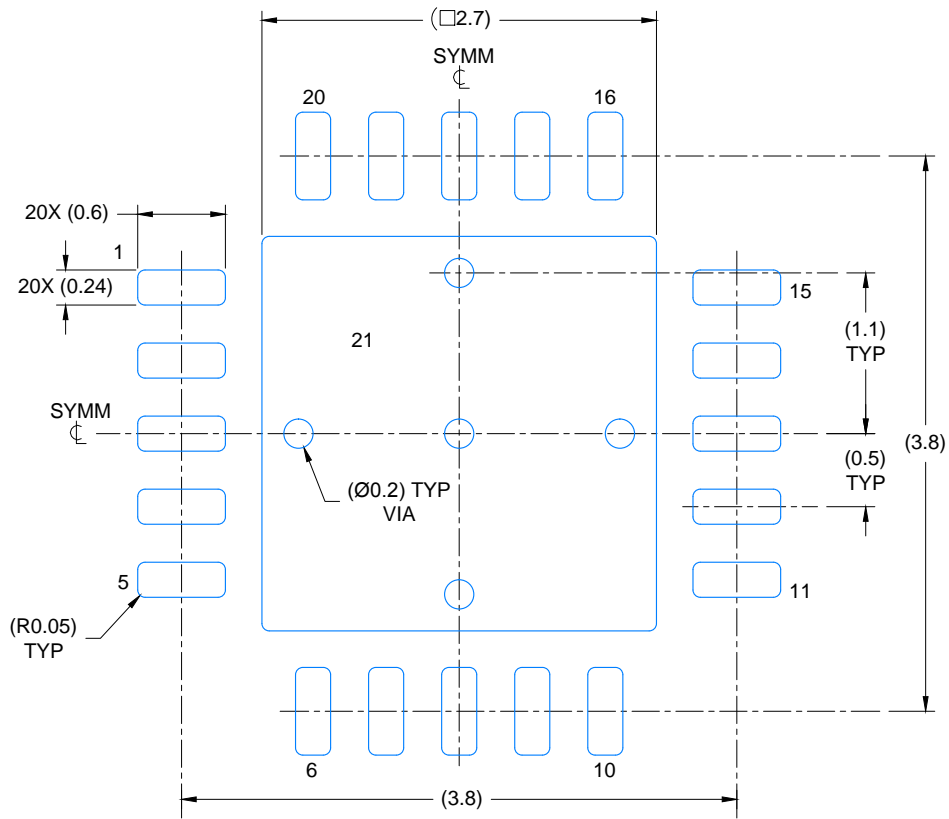


4219125 / A 10/2016

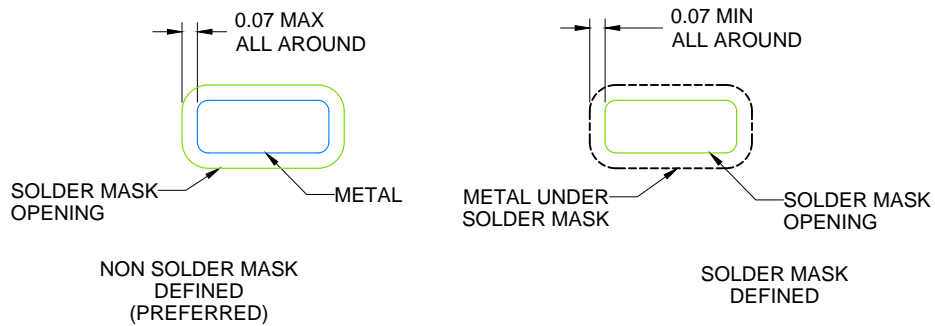
**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.





LAND PATTERN EXAMPLE  
SCALE: 20X

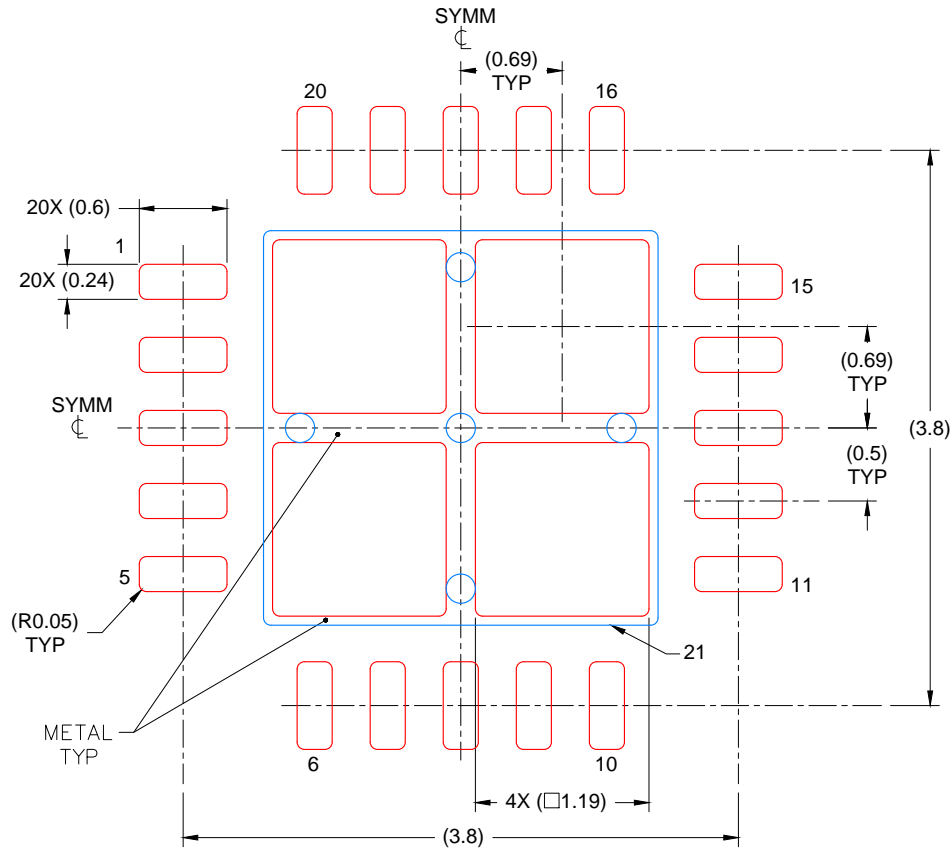


SOLDER MASK DETAILS

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NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



**SOLDER PASTE EXAMPLE**  
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
 78% PRINTED COVERAGE BY AREA  
 SCALE: 20X

4219125 / A 10/2016

NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations..

# REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTSMAN
A	RELEASE NEW DRAWING	2160736	10/24/2016	T. TANG / H. DENG

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